



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-03
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ACD1*UJ70AEA	A	CA2A	2015-09-03
Amount	UoM	Unit type	ST ECOPACK Grade	
128.0	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	8x8x1	56	flat	
Comment	Package: A0K7 TFLGA 8 X 8 X 1 56LD PITCH 0.5; MDF valid for STHV800L			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ACD1*UJ70AEA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	69.876	mg	supplier	die	Silicon (Si)	7440-21-3		69.317	mg	992000	541539				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.277	mg	3964	2164				
				supplier	passivation	Silicon Oxide	7631-86-9		0.003	mg	43	23				
				supplier	die polymer coat	PIX1 Gamma-butyrolactone	96-48-0		0.279	mg	3993	2180				
				substrate	Other Organic Materials	32.620	mg	supplier	core material	Fiber glass	65997-17-3		5.632	mg	172655	44000
								supplier	core material	Bisphenol F type epoxy resin	9003-36-5		3.136	mg	96137	24500
								supplier	core material	Bismaleimide (B)	105391-33-1		1.907	mg	58461	14898
								supplier	core material	Triazine (T)	25722-66-1		1.907	mg	58461	14898
								supplier	core material	metal hydroxide	21645-51-2		0.128	mg	3924	1000
								supplier	core material	Zinc hydroxyde	20427-58-1		0.026	mg	797	203
								supplier	core material	Calcium sulfate	7778-18-9		0.064	mg	1962	500
								supplier	Solder mask	Barium sulfate	7727-43-7		0.794	mg	24341	6203
								supplier	Solder mask	Acrylic resin	9003-01-4		1.232	mg	37768	9625
								supplier	Solder mask	Epoxy resin	29690-82-2		0.969	mg	29706	7570
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6		0.599	mg	18363	4680								
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6		0.462	mg	14163	3609								
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8		0.132	mg	4047	1031								
supplier	Solder mask	Amorphous silica	7631-86-9		0.088	mg	2698	688								
supplier	Solder mask	3-methyl-methoxy-buthyl	103429-90-9		0.059	mg	1809	461								
supplier	Solder mask	Silica Cristobalite	14464-46-1		0.044	mg	1349	344								
supplier	Solder mask	Copper Phthalocyanine	14302-13-7		0.001	mg	31	8								
supplier	Solder mask	Morpholine derivative	Proprietary		0.022	mg	674	172								
supplier	Solder mask	Chlorine	22537-15-1		0.001	mg	31	8								
supplier	metallisation	Copper (Cu)	7440-50-8		15.265	mg	467964	119258								
supplier	metallisation	Nickel (Ni)	7440-02-0		0.134	mg	4108	1047								
supplier	metallisation	Gold (Au)	7440-57-5		0.018	mg	552	141								
Die attach	Other inorganic materials	4.865	mg	supplier	glue	Silver (Ag)	7440-22-4		4.251	mg	873792	33211				
				supplier	glue	Neopentyl glycol dimethacrylate	1985-51-9		0.243	mg	49949	1898				
				supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.268	mg	55087	2094				
				supplier	glue	Ditrimethylolpropane tetraacrylate	94108-97-1		0.073	mg	15005	570				
				supplier	glue	Hydroquinone	123-31-9		0.002	mg	411	16				
				supplier	glue	palmitic acid	57-10-3		0.005	mg	1028	39				
				supplier	glue	4-tert-butylcyclohexanol	98-52-2		0.015	mg	3083	117				
				supplier	glue	Hexamethyltetracosane-hexaene	111-02-4		0.005	mg	1028	39				
				supplier	glue	Fluorine trace	14762-94-8		0.003	mg	617	23				
				Bonding wire	Precious metals	3.005	mg	supplier	wire	Gold (Au)	7440-57-5		2.975	mg	990017	23242
supplier	wire	Palladium (Pd)	7440-05-3						0.030	mg	9983	234				
encapsulation	Other Organic Materials	15.477	mg	supplier	mold compound	silica, vitreous	60676-86-0		14.207	mg	917943	110992				
				supplier	mold compound	Phenol resin	205830-20-2		0.619	mg	39995	4836				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.310	mg	20030	2422				
				supplier	mold compound	Oxirane, 2,2'(methylenebis(2,6-dimethyl-4,1-pi	93705-66-9		0.310	mg	20030	2422				
solder paste	Solder	0.277	mg	supplier	mold compound	carbon black	1333-86-4		0.031	mg	2003	242				
				supplier	solder	Tin (Sn)	7440-31-5		0.262	mg	945848	2047				
				supplier	solder	Silver (Ag)	7440-22-4		0.010	mg	36101	78				
				supplier	solder	Copper (Cu)	7440-50-8		0.002	mg	7220	16				
				supplier	solder	Flux residue	Proprietary		0.003	mg	10830	23				
Capacitors 0201	Other inorganic materials	1.880	mg	supplier	ceramic	Barium titanate oxide	12047-27-7		1.240	mg	659574	9688				
				supplier	insulator	Glass	65997-17-3		0.044	mg	23404	344				
				supplier	electrode	Copper (Cu)	7440-50-8		0.415	mg	220745	3242				
				supplier	metallisation	Nickel (Ni)	7440-02-0		0.073	mg	38830	570				
supplier	metallisation	Tin (Sn)	7440-31-5		0.108	mg	57447	844								